

ENGINEERING

DEPT.

PRODUCT SPECIFICATION For CJ01 Series Board Mound Telephone Jack

SPEC.NO.: SPCJ064A

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1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:

MIL - STD - 202Methods for test of connectors for electronic equipmentMIL - STD - 1344Test methods for electrical connectors

- 3. APPLICABLE SERIES NO.: CJ0188SM11SM
- 4. SHAPE, CONSTRUCTION AND DIMENSIONS See attached drawings
- 5. MATERIALS See attached drawings
- 6. ACCOMMODATED P.C.BOARD6.1 Thickness: 1.6 mm (.063")6.2 P.C. Board Layout: See attached drawings



REVIEWED : <u>Eisley</u> APPROVED : <u>Eisley</u> VERIFIED : <u>Sandy</u>.



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7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		1.5 A Max 150 V AC (r.m.s.)
7.2	Contact Resistance	Open circuit of DC 20 mV max. 100 mA max.	Less than 20 mΩ Max. (Initial)
		EIA-364-23B	Less than 30 mΩ Max. (Final)
7.3	Dielectric strength	Test between adjacent circuits of unmated connector.	No change
		When applied AC 1000 V 1 minute between adjacent contacts.	
		1.5KVrms at 60Hz or 2250VDC, 1 minute between shield and contacts	
		EIA-364-20B	
7.4	Insulation Resistance	When applied DC 500 V between adjacent terminal or ground	More than 500 M Ω Max. (Initial)
		EIA-364-21C	More than 200 MΩ Max. (Final)

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Contact Normal force	Individually pin of contact area EIA-364-04A	0.1Kgf Min.
8.2	Durability	Connector shall be subjected to 750 cycles of insertion and withdrawal EIA-364-09C	Appearance: No damage Contact resistance Less than 30 mΩ Max.
8.3	Mating force	Measure force to mate samples at speed 25±3mm per minute with plug latch depressed EIA-364-13B	 2 contacts: 1.6 Kgf Max. 4 contacts: 1.8 Kgf Max 6 contacts: 2.1 Kgf Max 8 contacts: 2.3 Kgf Max 10 contacts: 2.5 Kgf Max



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9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Humidity test	At a temperature of 40±2°C and relative humidity of 90-95% for 96 hours EIA-364-17B	Appearance: No damage Contact resistance Less than 30 mΩ Max.
9.2	Temperature Life	Exposing in a heat chamber at a temperature of 65±2°C for 96 hours EIA-364-17B	Appearance: No damage Contact resistance Less than 30 mΩ Max. Dielectric strength: To pass para 7-3
9.3	Salt spray	Temperature: 35±2°C Solution: 5±1% Spray time: 48 hours After test, rinse the sample with water and recondition the room temperature for 1 hour. EIA-364-26B	Appearance: No damage Contact resistance Less than 30 m Ω Max. Insulation resistance More than 200 M Ω Max.
9.4	Solder ability	Soldering time: 5±0.5 second Soldering pot: 245± 5°C	Minimum: 95% of immersed area
9.5	Resistance to soldering heat	Refer Reflow temperature profile(11.1)	Appearance: No damage

10. OPERATING TEMPERATURE RANGE: -40 to + 85 °C

- 11. Recommended IR Reflow Temperature Profile:
 - 11.1 Using Lead-Free Solder Past

